

FX 03020 US

OSP-14827

US 2/24 1/2

Docket No.

Armstrong, Westerman & Hattori, LLP

DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

SOLVENT-FREE MOISTURE-CURABLE HOT MELT URETHANE RESIN COMPOSITION

the specification of which is attached hereto unless the following is checked

☐ was filed on _____ as United States Application Number _____ or PCT International Application Number _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) - (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed.

Priority Claimed

(List prior foreign applications. See note A below)

2002-282885
(Number)

Japan
(Country)

27/09/2002
(Day/Month/Year Filed)

☒ Yes ☐ No

(Number)

(Country)

(Day/Month/Year Filed)

☐ Yes ☐ No

(Number)

(Country)

(Day/Month/Year Filed)

☐ Yes ☐ No

(Number)

(Country)

(Day/Month/Year Filed)

☐ Yes ☐ No

(See note B below)

☐ See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

Status

(List prior U.S. Applications)

(Application Serial No.)

(Filing Date)

☐ Patented ☐ Pending ☐ Abandoned

(Application Serial No.)

(Filing Date)

☐ Patented ☐ Pending ☐ Abandoned

(Application Serial No.)

(Filing Date)

☐ Patented ☐ Pending ☐ Abandoned

Ex 03020 US

OSP. 14000
USP 14000
2.6agent(s) to prosecute this application and to transact all business in
with:

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statements made herein of my own knowledge are true and that all statements made on
are believed to be true; and further that these statements were made with the knowledge that
ments and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the
Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any
issued thereon.

(see note C)

Full name of sole or first inventor (given name, family name)

Yukihiko Minamida

Inventor's signature

Yukihiko Minamida

Date September 16, 2003

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Citizenship Japan

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Full name of second inventor (given name, family name)

Masayoshi Imanaka

Inventor's signature

Masayoshi Imanaka

Date September 16, 2003

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Full name of third inventor (given name, family name)

Kojiro Tanaka

Inventor's signature

Kojiro Tanaka

Date September 16, 2003

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Full name of fourth inventor (given name, family name)

Inventor's signature

Date

Residence

Citizenship

Post Office Address

Full name of fifth inventor (given name, family name)

Inventor's signature

Date

Residence

Citizenship

Post Office Address